

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	39	(sadato near3 imai).in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:21
L2	42	(koichi near3 fukasawa).in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:15
L3	2	(nodoka near3 oishi).in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:11
L4	1350	(313/512).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:15
L5	672	(313/498).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:15
L6	1080	(257/E33.066).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:16
L7	124	(257/E33.056).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:17
L8	601	(257/E33.057).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:17
L9	361	(257/E33.058).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:17

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L10	986	(257/E33.059).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:17
L13	2687	(257/99).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:18
L14	1969	L13 and (@ad<"20030228" @rlad<"20030228")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:18
L15	255	L14 and (wire near (lead bond) wirebond)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:18
L16	830	L14 and wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:18
L17	601	(257/E33.057).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:18
L18	374	L17 and (@ad<"20030228" @rlad<"20030228")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:18
L19	1925	(257/79).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:18
L20	1166	L19 and (@ad<"20030228" @rlad<"20030228")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:28
L21	282	L20 and wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:18

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L22	2406	(257/784).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:18
L23	1948	L22 and (@ad<"20030228" @rlad<"20030228")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:18
L24	27	L23 and (light adj emitting adj (diode device element chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:26
L25	116	L23 and (laser adj diode LD LED light adj emitting adj (diode device element chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:18
L26	682	(257/E33.075).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:18
L27	361	(257/E33.058).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:18
L28	453	L26 and (@ad<"20030228" @rlad<"20030228")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:18
L29	282	L27 and (@ad<"20030228" @rlad<"20030228")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:18
L30	150	L29 not (L28 L25 L14 L24 L21 L18 L7 L16 L6 L15)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:18
L31	1076	L14 not (L21 L18 L7 L16 L6 L15)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:19

## EAST Search History

L32	1683	(257/706).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:24
L33	5955	(PCB print adj substrate printed adj circuit adj board) and light adj emitting adj (diode element device) and (enclosure package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:25
L34	1078	(257/707).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:25
L35	1022	(257/100).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/20 14:25
L36	151	((PCB print adj substrate printed adj circuit adj board) and light adj emitting adj (diode element device) and (enclosure package)). clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:25
L37	2966	heat adj sink and wire and (light adj emitting adj (diode device element chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:27
L38	96	(heat adj sink and wire and (light adj emitting adj (diode device element chip die))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:27
L39	1305	package and heat adj sink and wire and (light adj emitting adj (diode device element chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:27
L40	836	L39 and (@ad<"20030228" @rlad<"20030228")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 14:28